

PowerPAD™ PLASTIC SMALL-OUTLINE PACKAGE

Technical drawing of a thermal pad showing top, side, and detail views with dimensions and tolerances.

Top View Dimensions:

- Pin pitch: 0,50
- Pin diameter: 0,27 / 0,17
- Pin diameter tolerance: 0,08 (M)
- Pin count: 30
- Pin 1 indicator
- Pin 15 indicator
- Pin 16 indicator
- Overall width: A
- Overall height: 4,50 / 4,30 (nominal / tolerance) and 6,60 / 6,20 (nominal / tolerance)

Side View Dimensions:

- Seating Plane
- Pin height: 1,20 MAX
- Pin height tolerance: 0,15 / 0,05
- Pin height tolerance: 0,10

Detail View Dimensions:

- Pin height: 0,15 NOM
- Gage Plane
- Pin height: 0,25
- Pin height: 0,75 / 0,50
- Angle: 0°-8°

PINS ** DIM	28	30	38	44	50
A MAX	7,90	7,90	9,80	11,40	12,60
A MIN	7,70	7,70	9,60	11,20	12,40

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions include mold flash or protrusions.
 - D. The package thermal performance may be enhanced by attaching an external heatsink to the thermal pad. This pad is electrically and thermally connected to the backside of the die and possibly selected leads.
 - E. Falls within JEDEC MO-153

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